10/042,408

L Number	Hits		DB	Time stamp
5	669		USPAT;	2004/10/29 12:52
		and @ad<19940318) and wire) and (encapsula\$5	US-PGPUB;	
		epoxy resin packag\$3)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
6	81	(((((ball adj grid) BGA PGA (pin adj grid))	USPAT;	2004/10/29 12:47
	01	and @ad<19940318) and wire) and (encapsula\$5	US-PGPUB;	
		epoxy resin packag\$3)) and wafer	EPO; JPO;	
		epoxy resin packagos, , and warer	DERWENT;	
			IBM TDB	
7	140	((ball adj grid) BGA PGA (pin adj grid)) and	USPAT:	2004/10/29 13:13
	140	((ball ad) grid) BGA PGA (pin ad) grid) and @ad<19940318 and wafer		2004/10/29 13:13
		@ad<19940318 and water	US-PGPUB;	!
			EPO; JPO;	
			DERWENT;	
		1	IBM_TDB	
8	103	(substrate near8 pattern\$3) and @ad<19940318	USPAT;	2004/10/29 13:15
		and (BGA PGA)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
9	146	((metal\$8 wir\$3) near8 pattern\$3) and	USPAT;	2004/10/29 13:23
		@ad<19940318 and (BGA PGA)	US-PGPUB;	, ,
		Gaariy 10310 and (2011 1011)	EPO; JPO;	İ
			DERWENT;	
			IBM TDB	
10	_	//matales	USPAT;	2004/10/29 13:24
	U	((metal\$8 wir\$3) near8 (repeat\$4 adj	1	2004/10/29 13:24
		pattern\$3)) and @ad<19940318 and (BGA PGA)	US-PGPUB;	
		•	EPO; JPO;	i '
			DERWENT;	
			IBM_TDB	
11	100		USPAT;	2004/10/29 13:25
		pattern\$3)) and @ad<19940318	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
12	34	(((metal\$8 wir\$3) near8 (repeat\$4 adj	USPAT;	2004/10/29 14:05
		pattern\$3)) and @ad<19940318) and substrate	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
13	4	(("5729894") or ("5578869")).PN.	USPAT:	2004/10/29 14:06
	"	(\ 5.25054 OI \ 55.0005 1.1M.	US-PGPUB;	=302, 23, 23
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
		//h-13 - 4444\ DON DON /	_	2004/10/20 10 55
-	3828	((ball adj grid) BGA PGA (pin adj grid)) and	USPAT;	2004/10/29 10:55
i		@ad<19940318	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	844		USPAT;	2004/10/29 10:55
		and @ad<19940318) and wire	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	669	((((ball adj grid) BGA PGA (pin adj grid))	USPAT;	2004/10/29 12:46
	609	and @ad<19940318) and wire) and (encapsula\$5	US-PGPUB;	-301, 10, 20 12.40
			1	
		epoxy resin packag\$3)	EPO; JPO;	
			DERWENT;	
	i		IBM TDB	1